

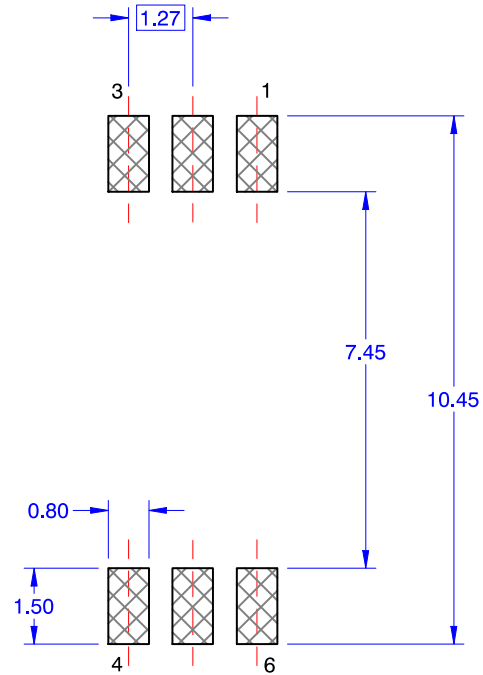
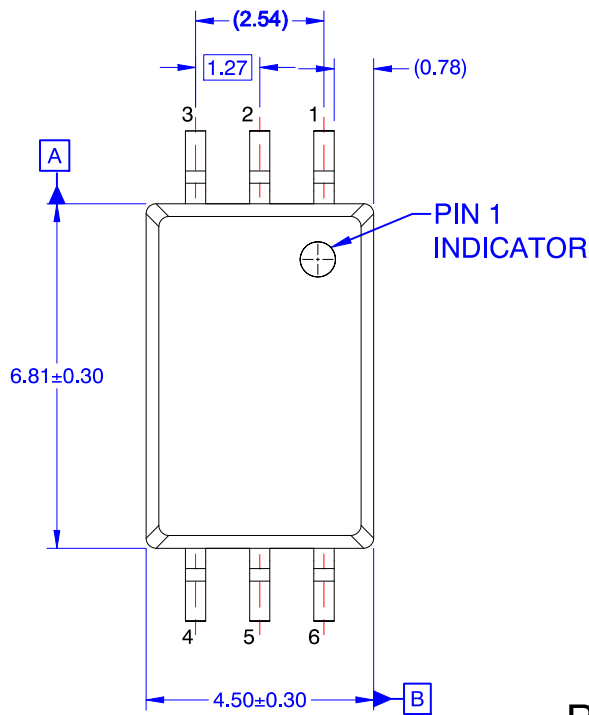
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

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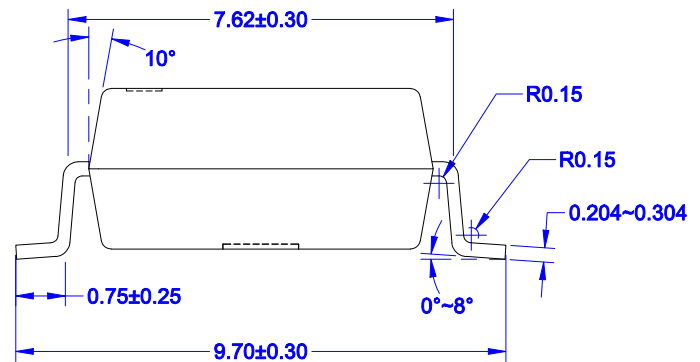
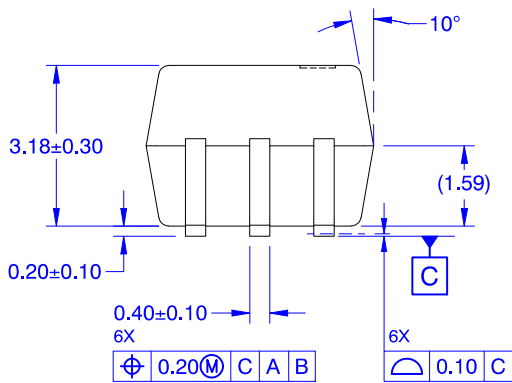


SOIC6
CASE 751EL
ISSUE O

DATE 30 SEP 2016



RECOMMENDED LAND PATTERN



NOTES: UNLESS OTHERWISE SPECIFIED

- A) NO STANDARD APPLIES TO THIS PACKAGE
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH, AND TIE BAR EXTRUSION.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.

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